



A New Direction in Mixed-Signal

XR1008, XR2008

0.5mA, 75MHz Rail-to-Rail Amplifiers

General Description

The XR1008 (single) and XR2008 (dual) are rail-to-rail output amplifiers that offer superior dynamic performance with 75MHz small signal bandwidth and 50V/ μ s slew rate. The XR1008 and XR2008 amplifiers consume only 505 μ A of supply current per channel and are designed to operate from a supply range of 2.5V to 5.5V (± 1.25 to ± 2.75).

The combination of low power, high output current drive, and rail-to-rail performance make the XR1008 and XR2008 well suited for battery-powered metering and test equipment.

The combination of low cost and high performance make these amplifiers suitable for high volume industrial applications such as ultrasonic heat meters, water meters and other applications requiring high speed and low power.

FEATURES

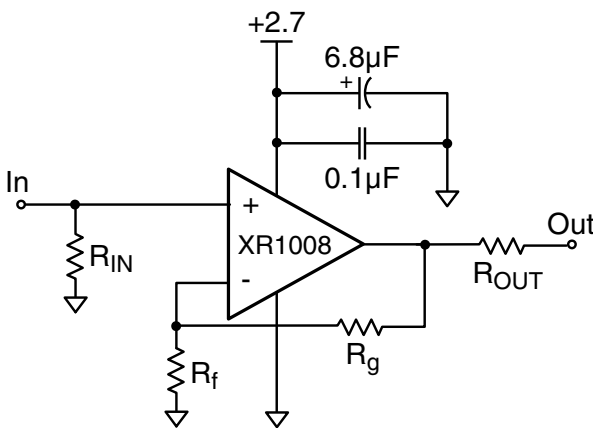
- 505 μ A supply current
- 75MHz bandwidth
- Input voltage range with 5V supply: -0.3V to 3.8V
- Output voltage range with 5V supply: 0.07V to 4.86V
- 50V/ μ s slew rate
- 12nV/ $\sqrt{\text{Hz}}$ input voltage noise
- 15mA linear output current
- Fully specified at 2.7V and 5V supplies

APPLICATIONS

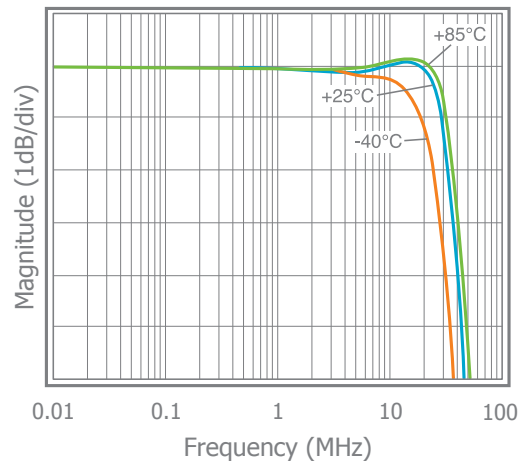
- Portable/battery-powered applications
- Mobile communications, cell phones, pagers
- ADC buffer
- Active filters
- Portable test instruments
- Signal conditioning
- Medical equipment
- Portable medical instrumentation
- Flow meters

Ordering Information - [back page](#)

Typical Application



Frequency Response vs. Temperature



Absolute Maximum Ratings

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

V_S 0V to 6V
 V_{IN} $-V_S - 0.5V$ to $+V_S + 0.5V$
 Continuous Output Current -30mA to +30mA

Operating Conditions

Supply Voltage Range2.5 to 5.5V
 Operating Temperature Range-40°C to 125°C
 Junction Temperature 150°C
 Storage Temperature Range.....-65°C to 150°C
 Lead Temperature (Soldering, 10s)260°C

Package Thermal Resistance

θ_{JA} (TSOT-5)215°C/W
 θ_{JA} (SOIC-8) 150°C/W
 θ_{JA} (MSOP-8) 200°C/W
 Package thermal resistance (θ_{JA}), JEDEC standard, multi-layer test boards, still air.

ESD Protection

XR1008 (HBM)2kV
 XR2008 (HBM)2.5kV
 ESD Rating for HBM (Human Body Model).

Electrical Characteristics at +2.7V

$T_A = 25^\circ\text{C}$, $V_S = +2.7\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---------------------------|------------------------------|---|-----|--------------|-----|------------------------------|
| Frequency Domain Response | | | | | | |
| UGBW _{SS} | Unity Gain -3dB Bandwidth | $G = +1$, $V_{OUT} = 0.05V_{pp}$, $R_f = 0$ | | 65 | | MHz |
| BW _{SS} | -3dB Bandwidth | $G = +2$, $V_{OUT} < 0.2V_{pp}$ | | 30 | | MHz |
| BW _{LS} | Large Signal Bandwidth | $G = +2$, $V_{OUT} = 2V_{pp}$ | | 12 | | MHz |
| GBWP | Gain Bandwidth Product | $G = +11$, $V_{OUT} = 0.2V_{pp}$ | | 28 | | MHz |
| Time Domain Response | | | | | | |
| t_R , t_F | Rise and Fall Time | $V_{OUT} = 0.2\text{V}$ step; (10% to 90%) | | 7.5 | | ns |
| t_S | Settling Time to 0.1% | $V_{OUT} = 1\text{V}$ step | | 60 | | ns |
| OS | Overshoot | $V_{OUT} = 1\text{V}$ step | | 10 | | % |
| SR | Slew Rate | $G = -1$, 2V step | | 40 | | V/ μs |
| Distortion/Noise Response | | | | | | |
| HD2 | 2nd Harmonic Distortion | 1MHz, $V_{OUT} = 1V_{pp}$ | | -67 | | dBc |
| HD3 | 3rd Harmonic Distortion | 1MHz, $V_{OUT} = 1V_{pp}$ | | -72 | | dBc |
| THD | Total Harmonic Distortion | 1MHz, $V_{OUT} = 1V_{pp}$ | | 65 | | dB |
| e_n | Input Voltage Noise | >10kHz | | 12 | | nV/ $\sqrt{\text{Hz}}$ |
| DC Performance | | | | | | |
| V_{IO} | Input Offset Voltage | | | 0 | | mV |
| d_{VIO} | Average Drift | | | 10 | | $\mu\text{V}/^\circ\text{C}$ |
| I_B | Input Bias Current | | | 1.2 | | μA |
| dI_B | Average Drift | | | 3.5 | | nA/ $^\circ\text{C}$ |
| I_{OS} | Input Offset Current | | | 30 | | nA |
| PSRR | Power Supply Rejection Ratio | DC | 60 | 66 | | dB |
| A_{OL} | Open Loop Gain | $V_{OUT} = V_S / 2$ | | 98 | | dB |
| I_S | Supply Current | per channel | | 470 | | μA |
| Input Characteristics | | | | | | |
| R_{IN} | Input Resistance | Non-inverting | | 9 | | M Ω |
| C_{IN} | Input Capacitance | | | 1.5 | | pF |
| CMIR | Common Mode Input Range | | | -0.3 to 1.5 | | V |
| CMRR | Common Mode Rejection Ratio | DC, $V_{CM} = 0\text{V}$ to $V_S - 1.5\text{V}$ | | 74 | | dB |
| Output Characteristics | | | | | | |
| V_{OUT} | Output Voltage Swing | $R_L = 1\text{k}\Omega$ to $V_S / 2$ | | 0.09 to 2.53 | | V |
| | | $R_L = 10\text{k}\Omega$ to $V_S / 2$ | | 0.05 to 2.6 | | V |
| I_{OUT} | Output Current | | | ± 15 | | mA |
| I_{SC} | Short Circuit Current | | | ± 30 | | mA |

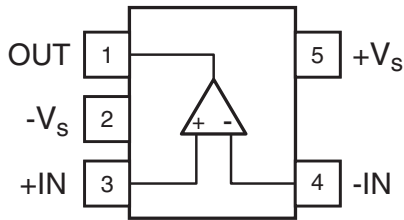
Electrical Characteristics at +5V

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---------------------------|------------------------------|---|-------------|--------------|-----|------------------------------|
| Frequency Domain Response | | | | | | |
| UGBW _{SS} | Unity Gain -3dB Bandwidth | $G = +1$, $V_{OUT} = 0.05V_{pp}$, $R_f = 0$ | | 75 | | MHz |
| BW _{SS} | -3dB Bandwidth | $G = +2$, $V_{OUT} < 0.2V_{pp}$ | | 35 | | MHz |
| BW _{LS} | Large Signal Bandwidth | $G = +2$, $V_{OUT} = 2V_{pp}$ | | 15 | | MHz |
| GBWP | Gain Bandwidth Product | $G = +11$, $V_{OUT} = 0.2V_{pp}$ | | 33 | | MHz |
| Time Domain Response | | | | | | |
| t_R , t_F | Rise and Fall Time | $V_{OUT} = 0.2\text{V}$ step; (10% to 90%) | | 6 | | ns |
| t_S | Settling Time to 0.1% | $V_{OUT} = 1\text{V}$ step | | 60 | | ns |
| OS | Overshoot | $V_{OUT} = 1\text{V}$ step | | 12 | | % |
| SR | Slew Rate | $G = -1$, 2V step | | 50 | | V/ μs |
| Distortion/Noise Response | | | | | | |
| HD2 | 2nd Harmonic Distortion | 1MHz, $V_{OUT} = 2V_{pp}$ | | -64 | | dBc |
| HD3 | 3rd Harmonic Distortion | 1MHz, $V_{OUT} = 2V_{pp}$ | | -62 | | dBc |
| THD | Total Harmonic Distortion | 1MHz, $V_{OUT} = 2V_{pp}$ | | 60 | | dB |
| e_n | Input Voltage Noise | >10kHz | | 12 | | nV/ $\sqrt{\text{Hz}}$ |
| DC Performance | | | | | | |
| V_{IO} | Input Offset Voltage | | -5 | -1 | 5 | mV |
| d_{VIO} | Average Drift | | | 10 | | $\mu\text{V}/^\circ\text{C}$ |
| I_B | Input Bias Current | | -3.5 | 1.2 | 3.5 | μA |
| dI_B | Average Drift | | | 3.5 | | nA/ $^\circ\text{C}$ |
| I_{OS} | Input Offset Current | | | 30 | 350 | nA |
| PSRR | Power Supply Rejection Ratio | DC | 60 | 66 | | dB |
| A_{OL} | Open Loop Gain | $V_{OUT} = V_S / 2$ | 65 | 80 | | dB |
| I_S | Supply Current | per channel | | 505 | 620 | μA |
| Input Characteristics | | | | | | |
| R_{IN} | Input Resistance | Non-inverting | | 9 | | M Ω |
| C_{IN} | Input Capacitance | | | 1.5 | | pF |
| CMIR | Common Mode Input Range | | | -0.3 to 3.8 | | V |
| CMRR | Common Mode Rejection Ratio | DC, $V_{CM} = 0\text{V}$ to $V_S - 1.5\text{V}$ | 65 | 74 | | dB |
| Output Characteristics | | | | | | |
| V_{OUT} | Output Voltage Swing | $R_L = 1\text{k}\Omega$ to $V_S / 2$ | 0.2 to 4.65 | 0.13 to 4.73 | | V |
| | | $R_L = 10\text{k}\Omega$ to $V_S / 2$ | | 0.08 to 4.84 | | V |
| I_{OUT} | Output Current | | | ± 15 | | mA |
| I_{SC} | Short Circuit Current | | | ± 30 | | mA |

XR1008 Pin Configurations

TSOT-5

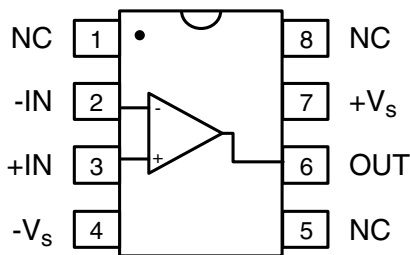


XR1008 Pin Assignments

TSOT-5

| Pin No. | Pin Name | Description |
|---------|----------|-----------------|
| 1 | OUT | Output |
| 2 | -Vs | Negative supply |
| 3 | +IN | Positive input |
| 4 | -IN | Negative input |
| 5 | +Vs | Positive supply |

SOIC-8

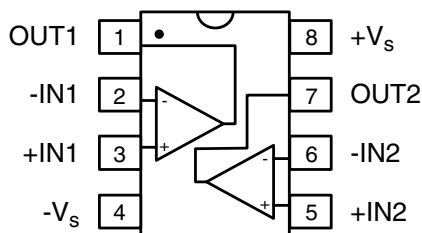


SOIC-8

| Pin No. | Pin Name | Description |
|---------|----------|-----------------|
| 1 | NC | No Connect |
| 2 | -IN | Negative input |
| 3 | +IN | Positive input |
| 4 | -Vs | Negative supply |
| 5 | NC | No Connect |
| 6 | OUT | Output |
| 7 | +Vs | Positive supply |
| 8 | NC | No Connect |

XR2008 Pin Configuration

SOIC-8 / MSOP-8



XR2008 Pin Assignments

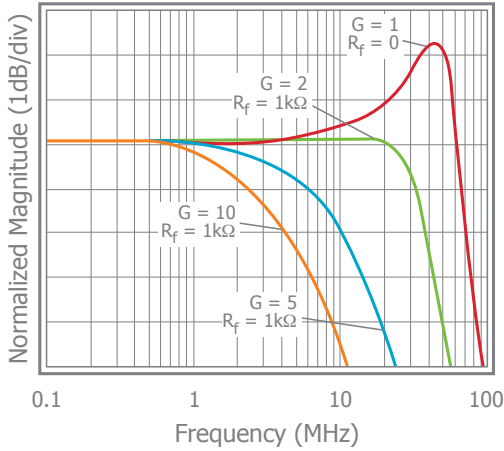
SOIC-8 / MSOP-8

| Pin No. | Pin Name | Description |
|---------|----------|---------------------------|
| 1 | OUT1 | Output, channel 1 |
| 2 | -IN1 | Negative input, channel 1 |
| 3 | +IN1 | Positive input, channel 1 |
| 4 | -Vs | Negative supply |
| 5 | +IN2 | Positive input, channel 2 |
| 6 | -IN2 | Negative input, channel 2 |
| 7 | OUT2 | Output, channel 2 |
| 8 | +Vs | Positive supply |

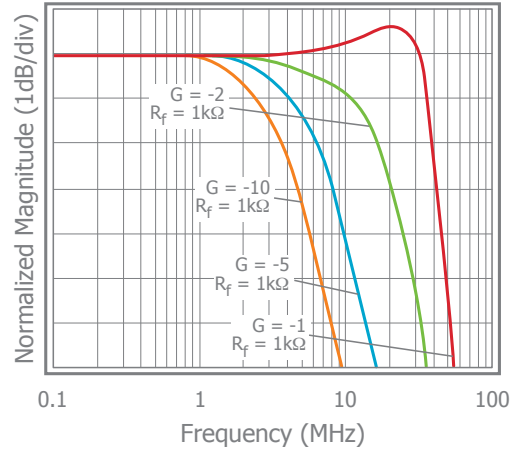
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

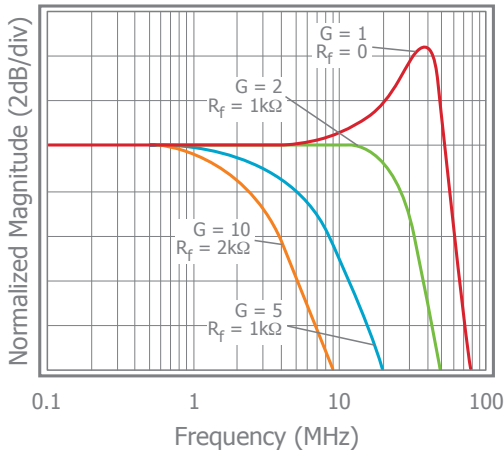
Non-Inverting Frequency Response at $V_S = 5\text{V}$



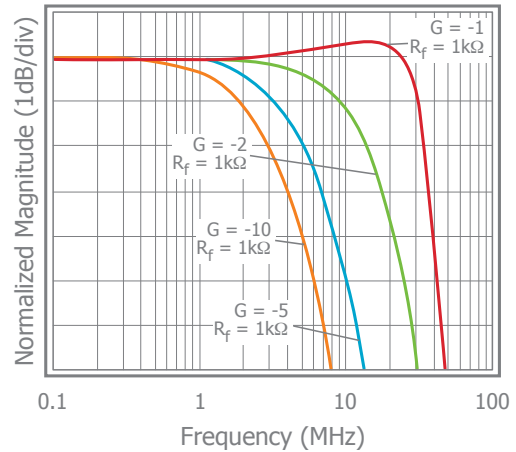
Inverting Frequency Response at $V_S = 5\text{V}$



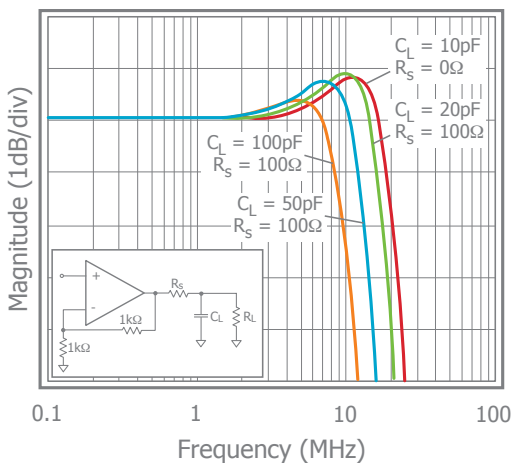
Non-Inverting Frequency Response at $V_S = 2.7\text{V}$



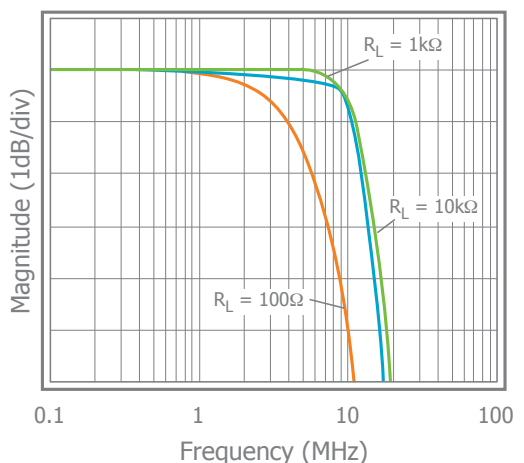
Inverting Frequency Response at $V_S = 2.7\text{V}$



Frequency Response vs C_L



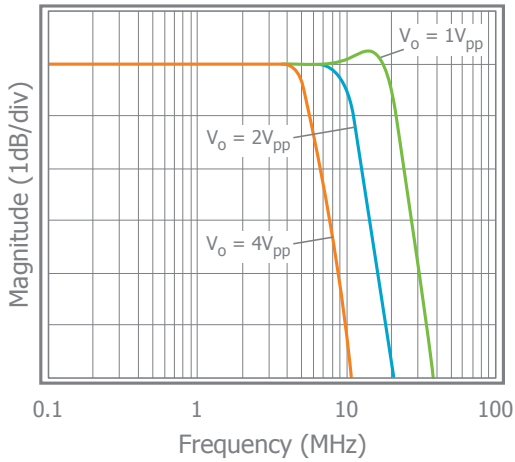
Frequency Response vs R_L



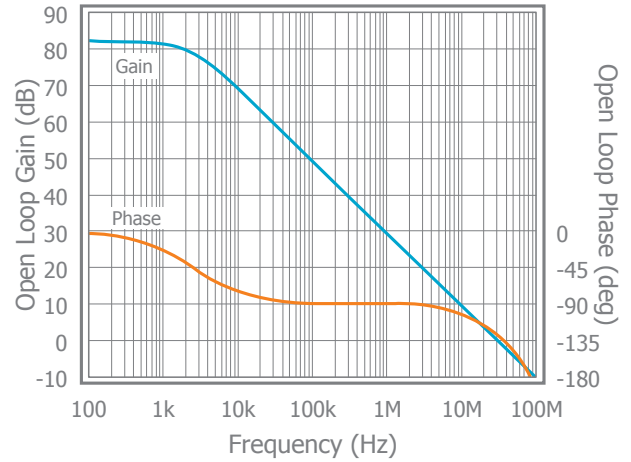
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

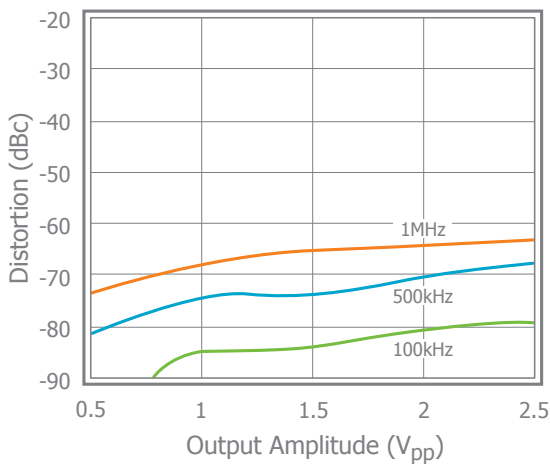
Frequency Response vs. V_{OUT}



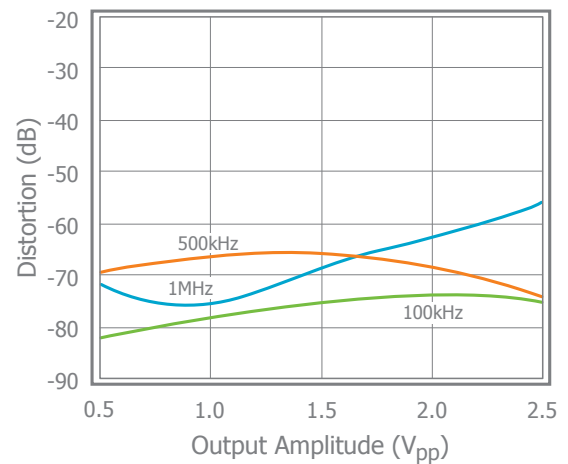
Open Loop Gain & Phase vs. Frequency



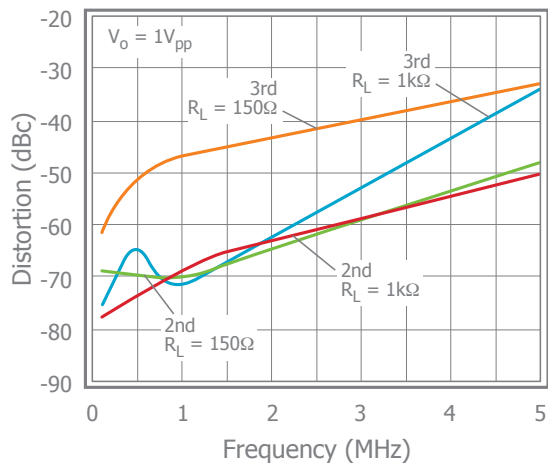
2nd Harmonic Distortion vs V_{OUT}



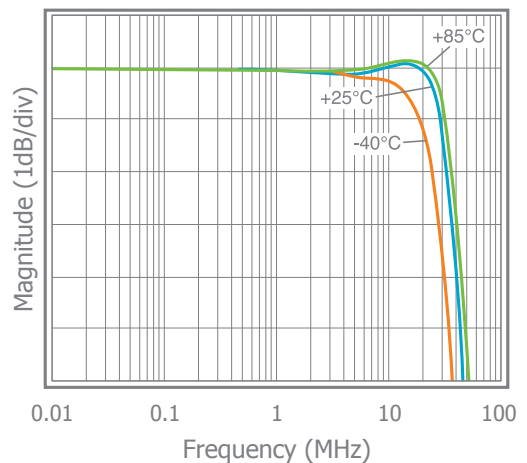
3rd Harmonic Distortion vs V_{OUT}



2nd & 3rd Harmonic Distortion at $V_S = 2.7\text{V}$



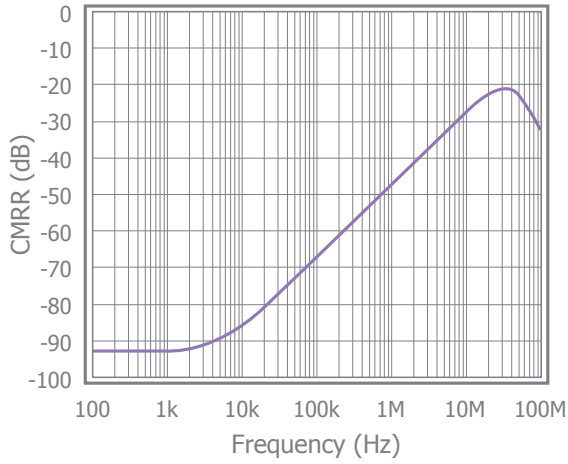
Frequency Response vs. Temperature



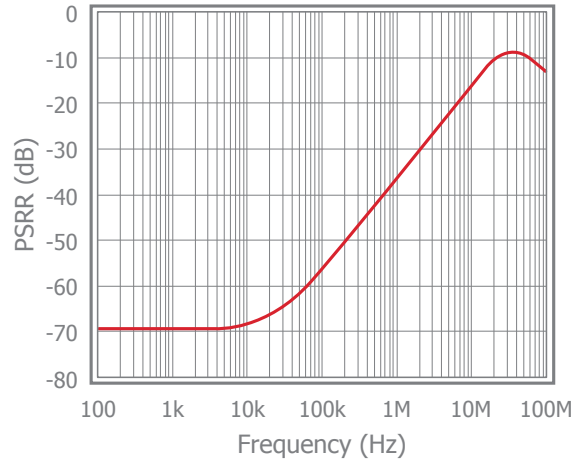
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

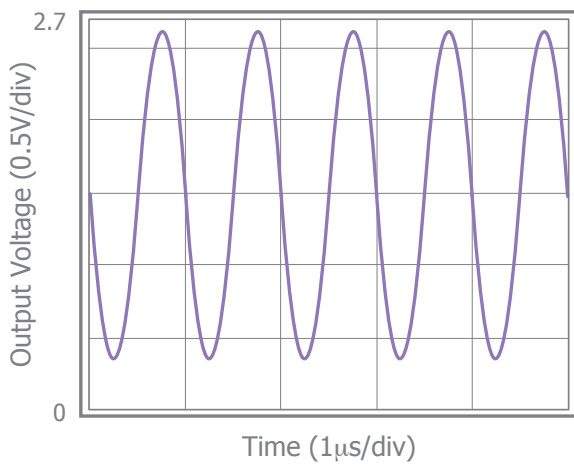
CMRR



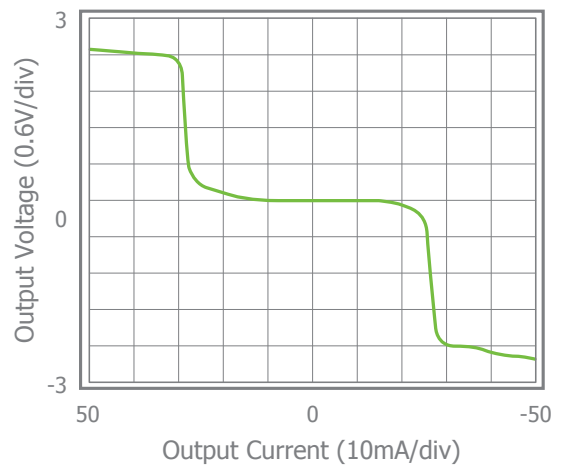
PSRR



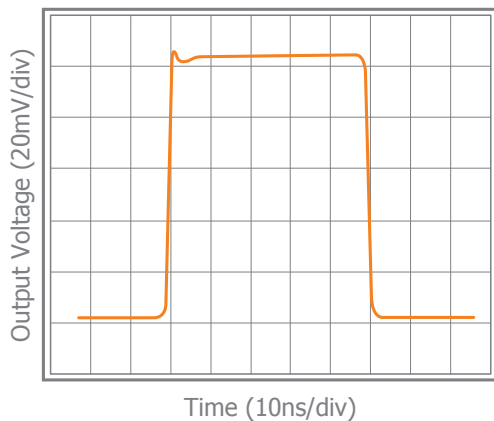
Output Swing



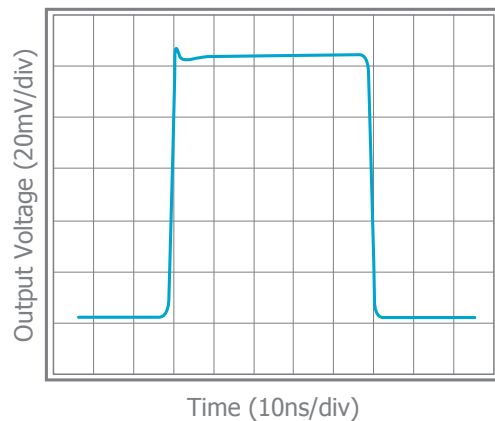
Output Voltage vs. Output Current



Small Signal Pulse Response at $V_S = 2.7\text{V}$



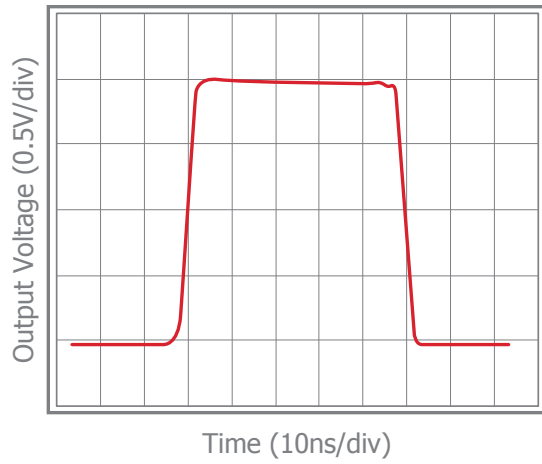
Small Signal Pulse Response at $V_S = 5\text{V}$



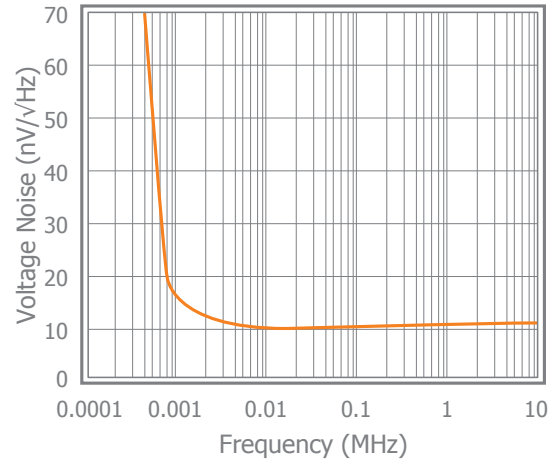
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 1\text{k}\Omega$, $R_L = 1\text{k}\Omega$ to $V_S/2$; $G = 2$; unless otherwise noted.

Large Signal Pulse Response at $V_S = 5\text{V}$



Input Voltage Noise



Application Information

General Description

The XR1008 family are a single supply, general purpose, voltage-feedback amplifiers fabricated on a complementary bipolar process. The XR1008 offers 75MHz unity gain bandwidth, 50V/μs slew rate, and only 505μA supply current. It features a rail-to-rail output stage and is unity gain stable.

Figures 1, 2, and 3 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations. Figure 4 shows the typical non-inverting gain circuit for single supply applications.

The common mode input range extends to 300mV below ground in single supply operation. Exceeding these values will not cause phase reversal. However, if the input voltage exceeds the rails by more than 0.5V, the input ESD devices will begin to conduct.

The design uses a Darlington output stage. The output stage is short circuit protected and offers “soft” saturation protection that improves recovery time.

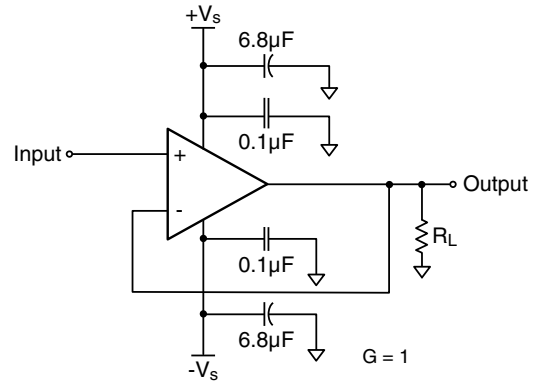


Figure 3: Unity Gain Circuit

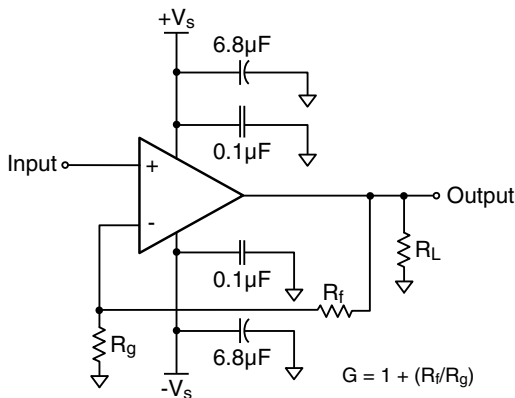


Figure 1: Typical Non-Inverting Gain Circuit

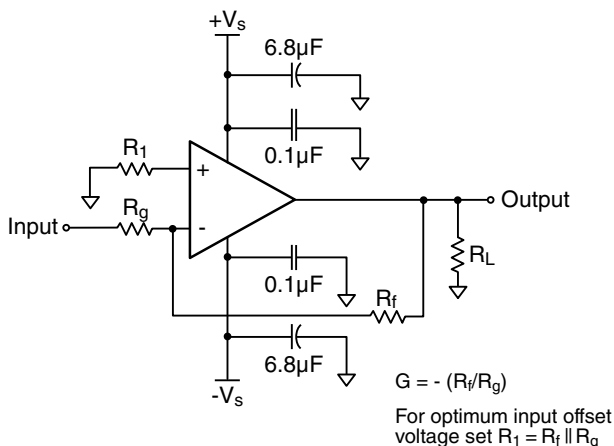


Figure 2: Typical Inverting Gain Circuit

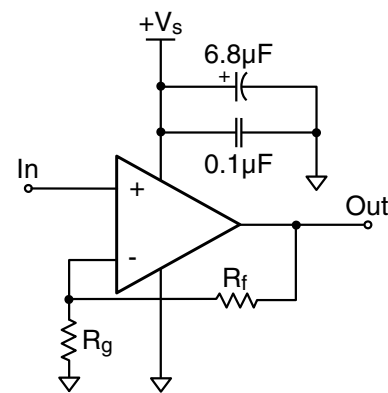


Figure 4: Single Supply Non-Inverting Gain Circuit

For optimum response at a gain of +2, a feedback resistor of 1kΩ is recommended. Figure 5 illustrates the XR1008 frequency response with both 1kΩ and 2kΩ feedback resistors.

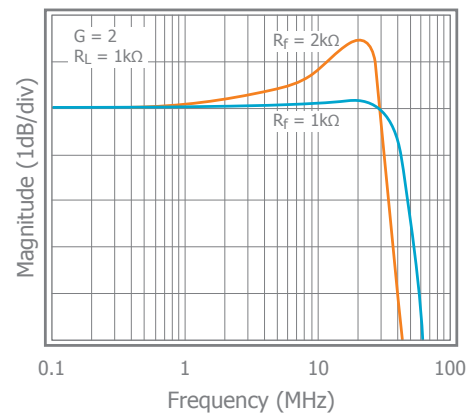


Figure 5: Frequency Response vs. R_f

Power Dissipation

Power dissipation should not be a factor when operating under the stated 1kΩ load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond its intended operating range.

Maximum power levels are set by the absolute maximum junction rating of 150°C. To calculate the junction temperature, the package thermal resistance value θ_{JA} (θ_{JA}) is used along with the total die power dissipation.

$$T_{\text{Junction}} = T_{\text{Ambient}} + (\theta_{JA} \times P_D)$$

Where T_{Ambient} is the temperature of the working environment.

In order to determine P_D , the power dissipated in the load needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{\text{supply}} - P_{\text{load}}$$

Supply power is calculated by the standard power equation.

$$P_{\text{supply}} = V_{\text{supply}} \times I_{\text{RMSsupply}}$$

$$V_{\text{supply}} = V_{S+} - V_{S-}$$

Power delivered to a purely resistive load is:

$$P_{\text{load}} = ((V_{\text{load}})_{\text{RMS}})^2 / R_{\text{load}_{\text{eff}}}$$

The effective load resistor ($R_{\text{load}_{\text{eff}}}$) will need to include the effect of the feedback network. For instance,

$R_{\text{load}_{\text{eff}}}$ in Figure 3 would be calculated as:

$$R_L \parallel (R_f + R_g)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load impedance is needed to determine the dissipated power. Here, P_D can be found from

$$P_D = P_{\text{Quiescent}} + P_{\text{Dynamic}} - P_{\text{load}}$$

Quiescent power can be derived from the specified I_S values along with known supply voltage, V_{supply} . Load power can be calculated as above with the desired signal amplitudes using:

$$(V_{\text{load}})_{\text{RMS}} = V_{\text{peak}} / \sqrt{2}$$

$$(I_{\text{load}})_{\text{RMS}} = (V_{\text{load}})_{\text{RMS}} / R_{\text{load}_{\text{eff}}}$$

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

$$P_{\text{Dynamic}} = (V_{S+} - V_{\text{load}})_{\text{RMS}} \times (I_{\text{load}})_{\text{RMS}}$$

Assuming the load is referenced in the middle of the power rails or $V_{\text{supply}}/2$.

The XR1008 is short circuit protected. However, this may not guarantee that the maximum junction temperature (+150°C) is not exceeded under all conditions. Figure 6 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

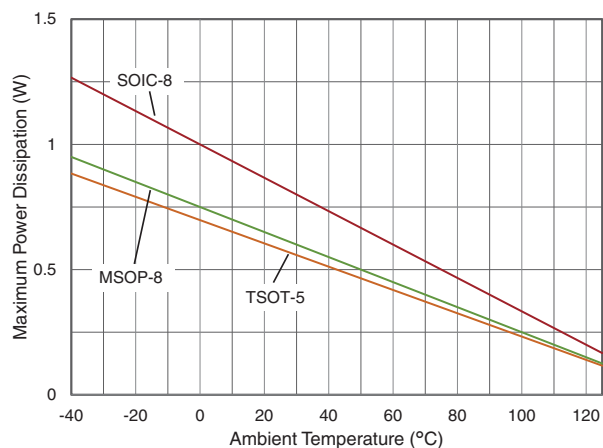


Figure 6. Maximum Power Derating

Driving Capacitive Loads

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance, R_S , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 7.

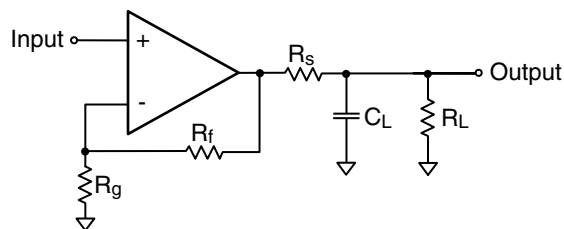


Figure 7. Addition of R_S for Driving Capacitive Loads

Table 1 provides the recommended R_S for various capacitive loads. The recommended R_S values result in approximately <1dB peaking in the frequency response.

| C_L (pF) | R_S (Ω) | -3dB BW (MHz) |
|------------|--------------------|---------------|
| 10pF | 0 | 22 |
| 20pF | 100 | 19 |
| 50pF | 100 | 12 |
| 100pF | 100 | 10.2 |

Table 1: Recommended R_S vs. C_L

For a given load capacitance, adjust R_S to optimize the tradeoff between settling time and bandwidth. In general, reducing R_S will increase bandwidth at the expense of additional overshoot and ringing.

Overdrive Recovery

For an amplifier, an overdrive condition occurs when the output and/or input ranges are exceeded. The recovery time varies based on whether the input or output is overdriven and by how much the ranges are exceeded. The XR1008, and XR2008 will typically recover in less than 20ns from an overdrive condition. Figure 5 shows the XR1008 in an overdriven condition.

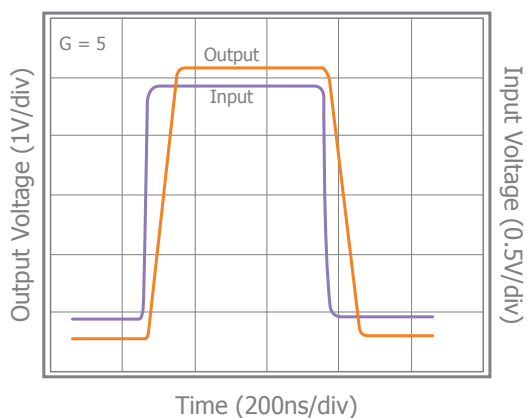


Figure 8: Overdrive Recovery

Layout Considerations

General layout and supply bypassing play major roles in high frequency performance. Exar has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8 μ F and 0.1 μ F ceramic capacitors for power supply decoupling
- Place the 6.8 μ F capacitor within 0.75 inches of the power pin
- Place the 0.1 μ F capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

Evaluation Board Information

The following evaluation boards are available to aid in the testing and layout of these devices:

| Evaluation Board # | Products |
|--------------------|----------------|
| CEB002 | XR1008 in TSOT |
| CEB003 | XR1008 in SOIC |
| CEB006 | XR2008 in SOIC |
| CEB010 | XR2008 in MSOP |

Evaluation Board Schematics

Evaluation board schematics and layouts are shown in Figures 9-18. These evaluation boards are built for dual-supply operation. Follow these steps to use the board in a single-supply application:

1. Short $-V_S$ to ground.
2. Use C3 and C4, if the $-V_S$ pin of the amplifier is not directly connected to the ground plane.

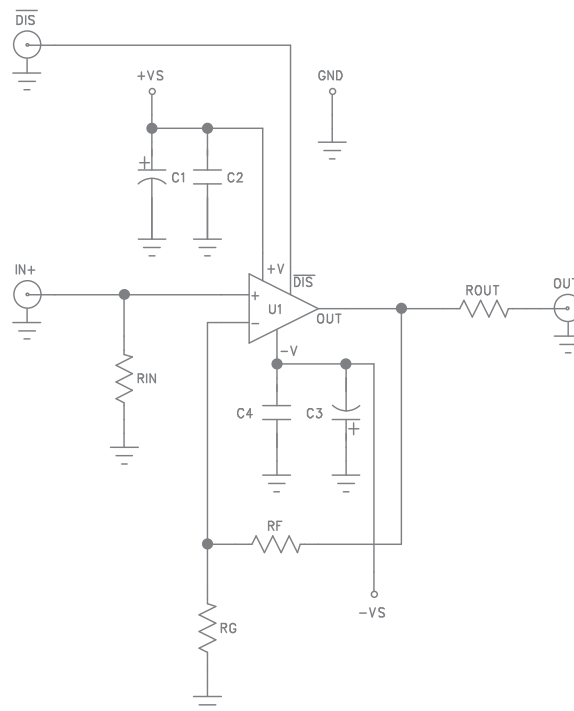


Figure 9. CEB002 & CEB003 Schematic

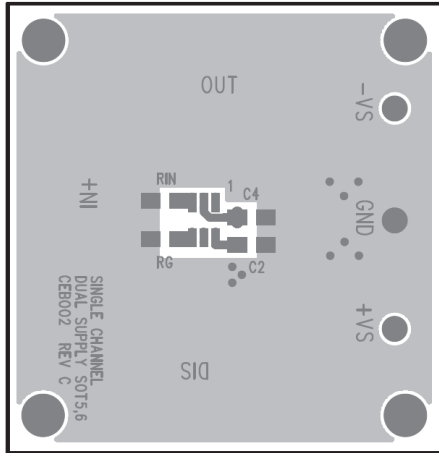


Figure 10. CEB002 Top View

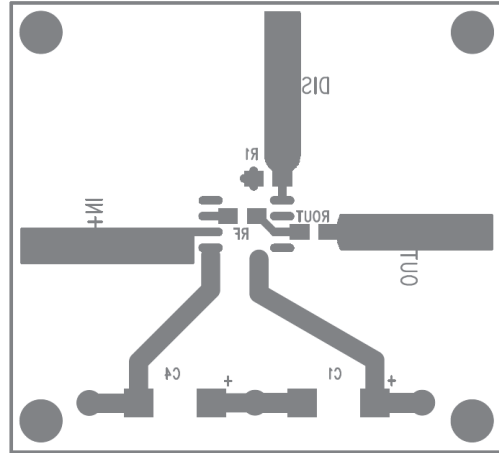


Figure 13. CEB003 Bottom View

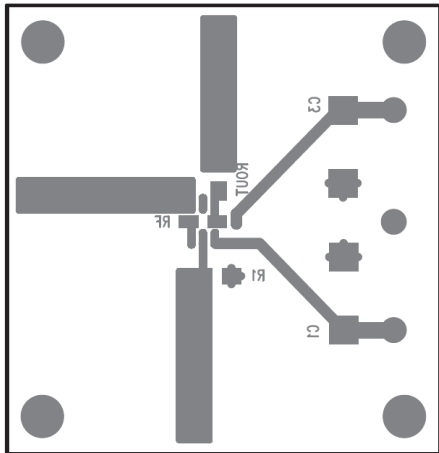


Figure 11. CEB002 Bottom View

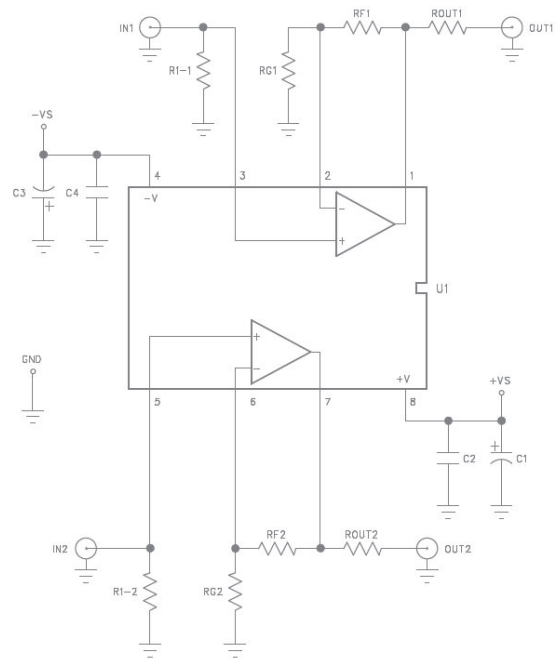


Figure 14. CEB006 & CEB010 Schematic

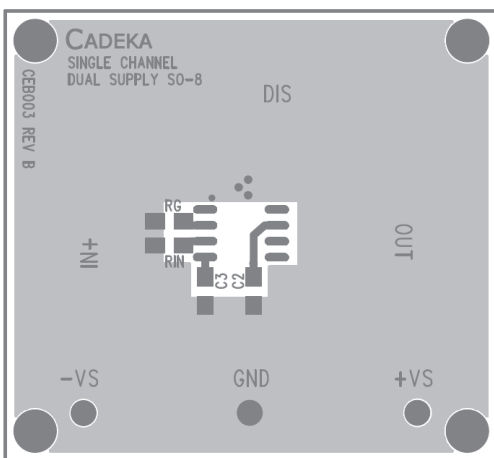


Figure 12. CEB003 Top View

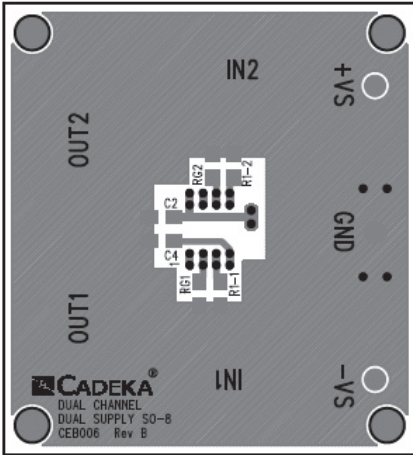


Figure 15. CEB006 Top View

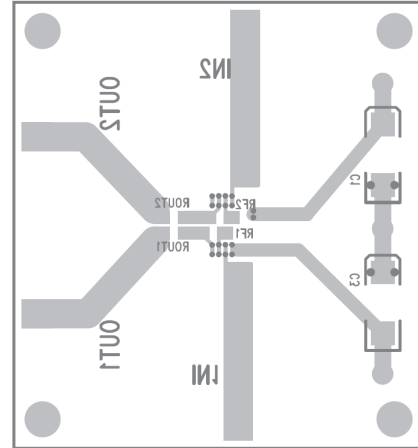


Figure 18. CEB010 Bottom View

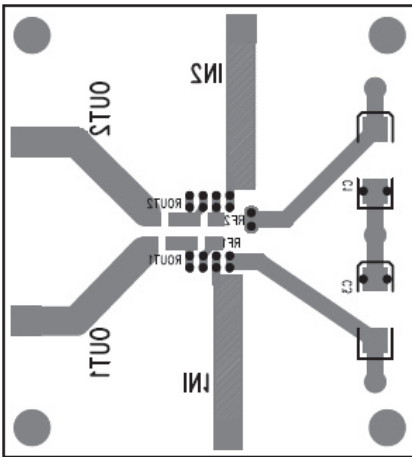


Figure 16. CEB006 Bottom View

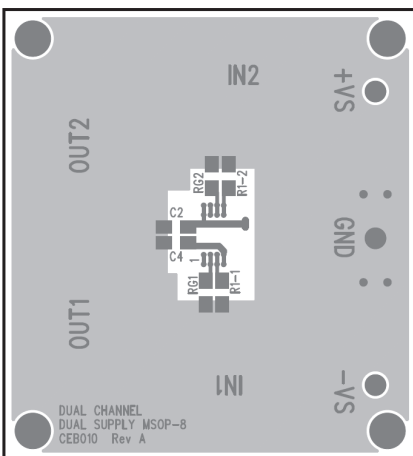
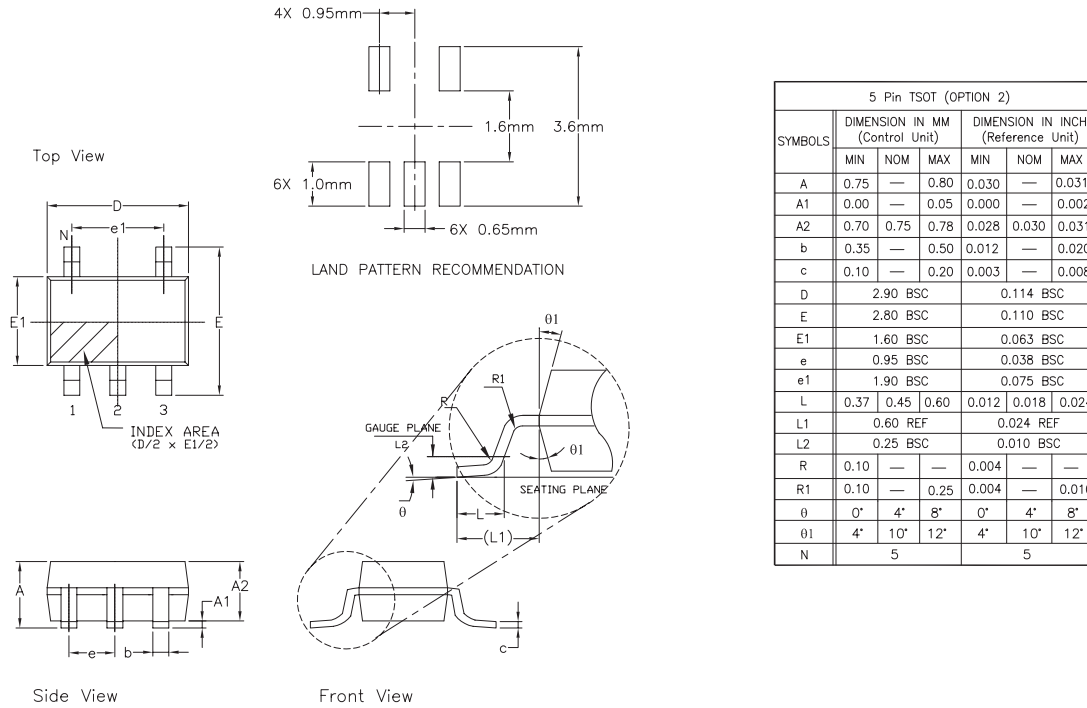


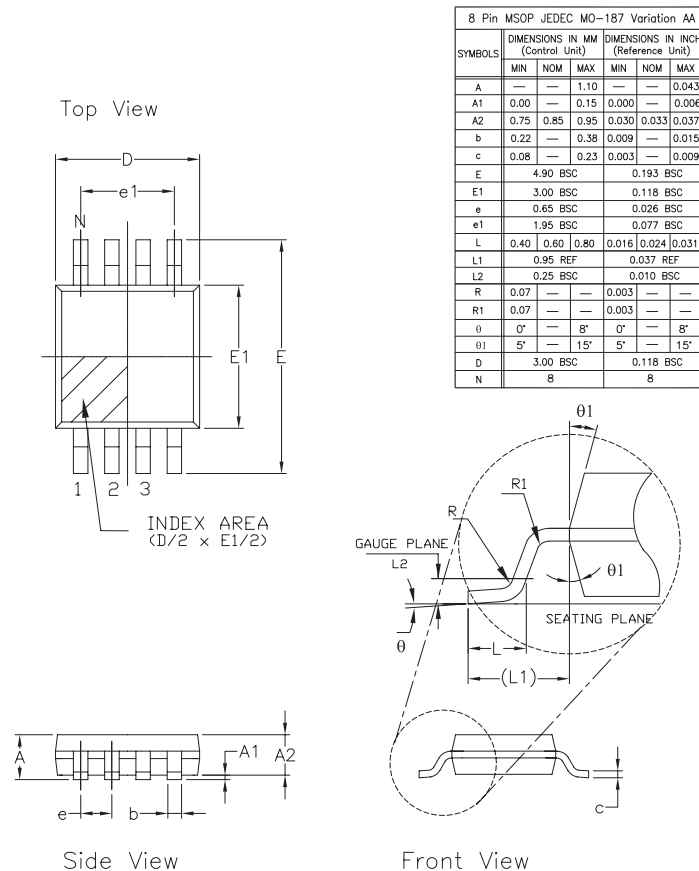
Figure 17. CEB010 Top View

Mechanical Dimensions

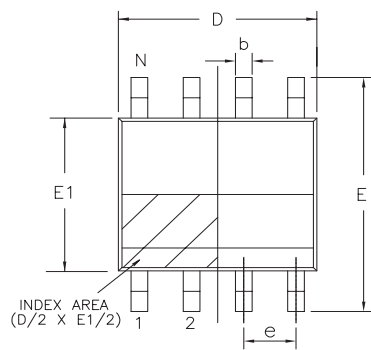
TSOT-5 Package



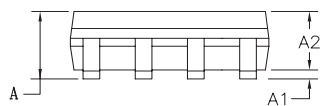
MSOP-8 Package



SOIC-8 Package

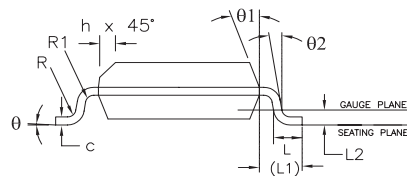
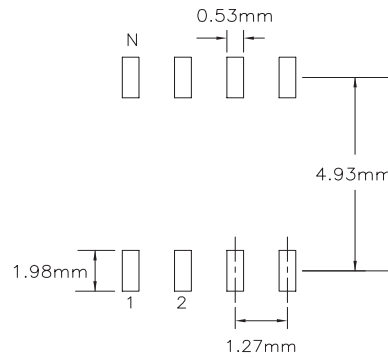


Top View



Side View

RECOMMENDED PCB LAND PATTERN



Front View

| 8 Pin SOICN JEDEC MS-012 Variation AA | | | | | | |
|---------------------------------------|------------------------------------|-----|------|--|-----|-------|
| SYMBOLS | DIMENSIONS IN MM (Control Unit) | | | DIMENSIONS IN INCH (Reference Unit) | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.35 | — | 1.75 | 0.053 | — | 0.069 |
| A1 | 0.10 | — | 0.25 | 0.004 | — | 0.010 |
| A2 | 1.25 | — | 1.65 | 0.049 | — | 0.065 |
| b | 0.31 | — | 0.51 | 0.012 | — | 0.020 |
| c | 0.17 | — | 0.25 | 0.007 | — | 0.010 |
| E | 6.00 BSC | | | 0.236 BSC | | |
| E1 | 3.90 BSC | | | 0.154 BSC | | |
| e | 1.27 BSC | | | 0.050 BSC | | |
| h | 0.25 | — | 0.50 | 0.010 | — | 0.020 |
| L | 0.40 | — | 1.27 | 0.016 | — | 0.050 |
| L1 | 1.04 REF | | | 0.041 REF | | |
| L2 | 0.25 BSC | | | 0.010 BSC | | |
| R | 0.07 | — | — | 0.003 | — | — |
| R1 | 0.07 | — | — | 0.003 | — | — |
| θ | 0° | — | 8° | 0° | — | 8° |
| θ1 | 5° | — | 15° | 5° | — | 15° |
| θ2 | 0° | — | — | 0° | — | — |
| D | 4.90 BSC | | | 0.193 BSC | | |
| N | 8 | | | 8 | | |

Ordering Information

| Part Number | Package | Green | Operating Temperature Range | Packaging Quantity | Marking |
|-----------------------------|------------------|-------|-----------------------------|--------------------|---------|
| XR1008 Ordering Information | | | | | |
| XR1008IST5X | TSOT-5 | Yes | -40°C to +125°C | 2.5k Tape & Reel | TC |
| XR1008IST5MTR | TSOT-5 | Yes | -40°C to +125°C | 250 Tape & Reel | TC |
| XR1008IST5EVB | Evaluation Board | N/A | N/A | N/A | N/A |
| XR1008ISO8X | SOIC-8 | Yes | -40°C to +125°C | 2.5k Tape & Reel | XR1008 |
| XR1008ISO8MTR | SOIC-8 | Yes | -40°C to +125°C | 250 Tape & Reel | XR1008 |
| XR1008ISO8EVB | Evaluation Board | N/A | N/A | N/A | N/A |
| XR2008 Ordering Information | | | | | |
| XR2008ISO8X | SOIC-8 | Yes | -40°C to +125°C | 2.5k Tape & Reel | XR2008 |
| XR2008ISO8MTR | SOIC-8 | Yes | -40°C to +125°C | 250 Tape & Reel | XR2008 |
| XR2008ISO8EVB | Evaluation Board | N/A | N/A | N/A | N/A |
| XR2008IMP8X | MSOP-8 | Yes | -40°C to +125°C | 2.5k Tape & Reel | 2008 |
| XR2008IMP8MTR | MSOP-8 | Yes | -40°C to +125°C | 250 Tape & Reel | 2008 |
| XR2008IMP8EVB | Evaluation Board | N/A | N/A | N/A | N/A |

Moisture sensitivity level for all parts is MSL-1.

Revision History

| Revision | Date | Description |
|----------|-----------|--|
| 1A | June 2014 | Initial Release [ECN1426-09 6/24/14] |
| 1B | Sept 2014 | Added XR1008 ESD, increased operating temperature range, updated package outline drawings, and removed Preliminary note on XR1008. [ECN1436-02 9/4/14] |

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Exar Technical Documentation: <http://www.exar.com/techdoc/>

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- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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